

PREVIOUS CUI DEVICE'S DETAIL / IMAGE

NEW CUI DEVICE'S DETAIL / IMAGE

SOLDERABILITY

| parameter | conditions/description | min | typ | max | units |
|--------------------------------|--|-----|-----|-----|-------|
| reel storage | at relative humidity <80% | | | 40 | °C |
| reflow soldering ¹ | see reflow profile | 255 | 260 | 265 | °C |
| drying conditions ² | parts in reel: bake at 40°C ±5°C for 72 hours parts removed from reel: bake at 40°C ±5°C for 10 hours | | | | |

Note: 1. It is recommended to reflow solder within 72 hours from opening vacuum packaging at a temperature >35°C & relative humidity <60%.
2. When exceeding flow life by >72 hours.

SOLDERABILITY

| parameter | conditions/description | min | typ | max | units |
|--------------------------------|--|-----|-----|-----|-------|
| reel storage | 10-30°C, <70% humidity | | | | °C |
| reflow soldering ¹ | see reflow profile | 255 | 260 | | °C |
| drying conditions ² | parts in reel: bake at 110°C for 4 hours parts removed from reel: bake at 110°C for 4 hours | | | | |

Note: 1. CUI Device recommends to solder within 72 hours from opening vacuum packaging at a temperature >35°C & relative humidity <60%.
2. When exceeding flow life by >1080 hours.

- * Time 25°C to Peak Temp. ----- 8 Minutes Max.
- * Time within 5°C of Actual Peak Temp. --- 20-40 Seconds


width: 6mm
Reel Size: Q300 mm
Reel QTY: 3,200 pcs per reel

Affected Date Code: **07/10/2023**

Product Availability: *Pertaining to market availability*

PCN Approval:

Operations/Quality



Product Management



F-723-001

Revision: A